

# P-Channel 12 V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)			
	$0.037$ at $V_{GS} = -4.5 \text{ V}$	- 7.3				
- 12	0.046 at V <sub>GS</sub> = - 2.5 V	- 6.6	19			
	0.060 at V <sub>GS</sub> = - 1.8 V	- 5.8				

### **FEATURES**

- TrenchFET® Power MOSFET
- MICRO FOOT® Chipscale Packaging Reduces Footprint Area Profile (0.62 mm) and On-Resistance Per Footprint Area

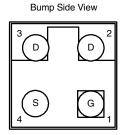


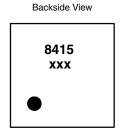
FREE

Ultra-Low On-Resistance

Material categorization: definitions compliance please see www.vishay.com/doc?99912

#### **MICRO FOOT**





ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)

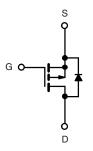
**Device Marking: 8415** 

xxx = Date/Lot Traceability Code

Ordering Information: Si8415DB-T1-E1 (Lead (Pb)-free and Halogen-free)

### **APPLICATIONS**

Load Switch, Charger Switch, and PA Switch for Portable Devices



P-Channel MOSFET

Parameter		Symbol	5 S	Steady State	Unit	
Drain-Source Voltage		V <sub>DS</sub>	- 12		V	
Gate-Source Voltage		V <sub>GS</sub>	± 8		]	
Continuous Dusin Courset /T 150 °C\d	T <sub>A</sub> = 25 °C	1-	- 7.3	- 5.3		
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>	T <sub>A</sub> = 70 °C	'D	- 5.9	- 4.3	^	
Pulsed Drain Current		I <sub>DM</sub>	- 25		^	
Continuous Source Current (Diodo Conduction) <sup>a</sup>		lo	- 25	-13		

Pulsed Drain Current		I <sub>DM</sub>	- 25		, ,
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	- 2.5	- 1.3	
Mariana Darra Diania atiang	T <sub>A</sub> = 25 °C	P <sub>D</sub>	2.77	1.47	w
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 70 °C	טי	1.77	0.94	VV
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 t	o 150	°C
Package Reflow Conditions <sup>b</sup>	IR/Convection		20	60	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Mariana baratian ta Ambianta	t ≤ 5 s	R <sub>thJA</sub>	35	45		
Maximum Junction-to-Ambient <sup>a</sup>	Steady State	' 'thJA	72	85	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	$R_{thJF}$	16	20		

- a. Surface mounted on 1" x 1" FR4 board.
- b. Refer to IPC/JEDEC (J-STD-020), no manual or hand soldering.
- c. In this document, any reference to case represents the body of the MICRO FOOT device and foot is the bump.



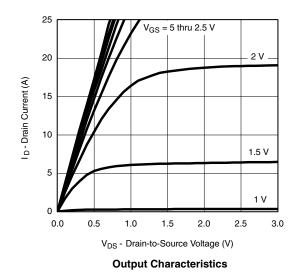
<b>SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C, unless otherwise noted)							
Parameter	Symbol	Test Conditions Mi		Тур.	Max.	Unit	
Static							
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = -250 \mu A$	- 0.4		- 1	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 8 V$			± 100	nA	
Zara Cata Valtaga Drain Current		V <sub>DS</sub> = - 12 V, V <sub>GS</sub> = 0 V			- 1	μΑ	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 12 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 70 °C			- 5		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 5			Α	
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 1 A		0.031	0.037		
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 1 A		0.038	0.046	Ω	
		V <sub>GS</sub> = - 1.8 V, I <sub>D</sub> = - 1 A		0.050	0.060		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 10 V, I <sub>D</sub> = - 1 A		11		S	
Diode Forward Voltage <sup>a</sup>	$V_{SD}$	I <sub>S</sub> = - 1 A, V <sub>GS</sub> = 0 V		- 0.8	- 1.1	V	
Dynamic <sup>b</sup>							
Total Gate Charge	$Q_g$			19	30		
Gate-Source Charge	$Q_{gs}$	$V_{DS} = -6 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -1 \text{ A}$		1.9		nC	
Gate-Drain Charge	$Q_{gd}$			4.8			
Gate Resistance	$R_{g}$	f = 1 MHz		19		Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			15	25		
Rise Time	t <sub>r</sub>	$V_{DD}$ = - 6 V, $R_L$ = 6 $\Omega$		32	50	1	
Turn-Off Delay Time	t <sub>d(off)</sub>	$\text{I}_\text{D}\cong$ - 1 A, $\text{V}_\text{GEN}$ = - 4.5 V, $\text{R}_\text{g}$ = 6 $\Omega$		180	270	ns	
Fall Time	t <sub>f</sub>			115	175		
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = - 1 A, dI/dt = 100 A/μs		80	120		

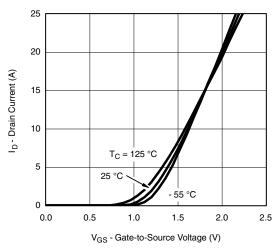
#### Notes:

- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

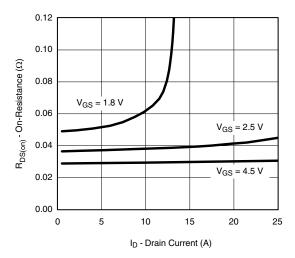
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



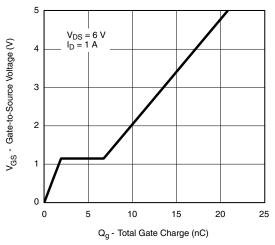




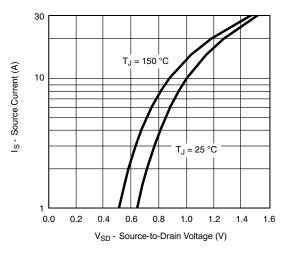
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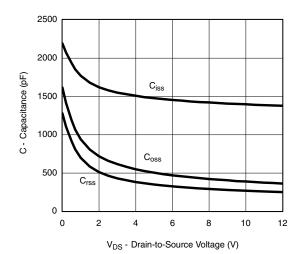
#### On-Resistance vs. Drain Current



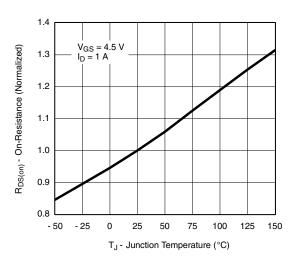
### **Gate Charge**



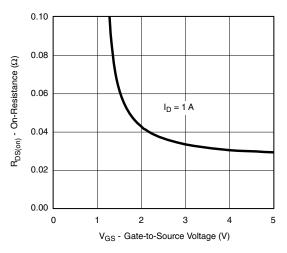
Source-Drain Diode Forward Voltage



Capacitance

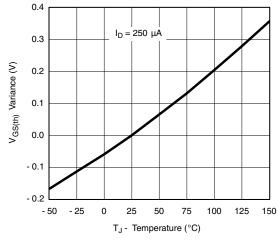


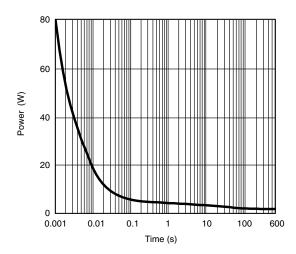
On-Resistance vs. Junction Temperature



On-Resistance vs. Gate-to-Source Voltage

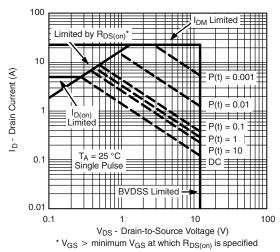
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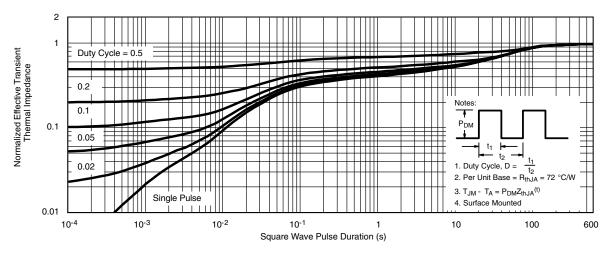


Threshold Voltage

Single Pulse Power, Junction-to-Ambient



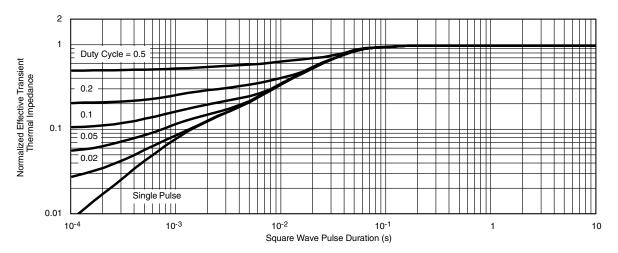




Normalized Thermal Transient Impedance, Junction-to-Ambient



# TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

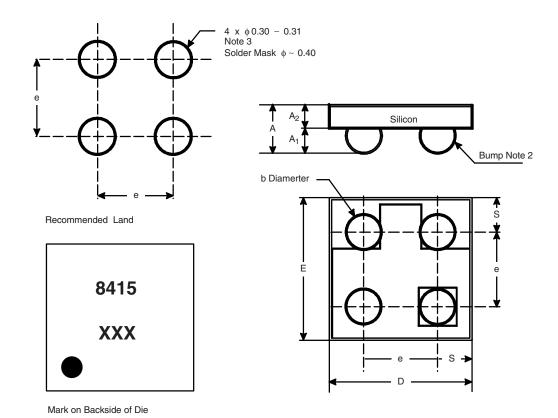


Normalized Thermal Transient Impedance, Junction-to-Foot

### **PACKAGE OUTLINE**

## MICRO FOOT: 4-BUMP (0.8 mm PITCH)





Notes (unless otherwise specified):

- 1. Laser mark on the silicon die back, coated with a thin metal.
- 2. Bumps are 95.5/3.8/0.7 Sn/Ag/Cu.
- 3. Non-solder mask defined copper landing pad.
- 4. The flat side of wafers is oriented at the bottom.

Dim.	Millim	neters <sup>a</sup>	Inches		
	Min.	Max.	Min.	Max.	
Α	0.600	0.650	0.0236	0.0256	
<b>A</b> <sub>1</sub>	0.260	0.290	0.0102	0.0114	
A <sub>2</sub>	0.340	0.360	0.0134	0.0142	
b	0.370	0.410	0.0146	0.0161	
D	1.520	1.600	0.0598	0.0630	
E	1.520	1.600	0.0598	0.0630	
е	0.800		0.0315		
S	0.360	0.400	0.0142	0.0157	

### Notes:

a. Use millimeters as the primary measurement.

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